

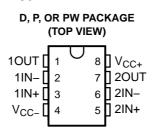
SLOS477A-JUNE 2005-REVISED JULY 2005

## **FEATURES**

- Operating Voltage...±2 V to ±18 V
- Low Offset Voltage...1 mV Max at 25°C, **TL5580A**
- Wide GBW...12 MHz Typ
- Slew Rate...5 V/µs Typ
- Low THD...0.0005% Typ
- Low-Noise Voltage...7 nV/VHz at 1 kHz Typ

#### **APPLICATIONS**

- Audio
- **Test Equipment**
- Industrial Process Controls
- **Data-Acquisition Systems**
- **Active Filters**
- **Power-Supply Regulation**



#### **DESCRIPTION/ORDERING INFORMATION**

The TL5580 is a dual bipolar operational amplifier that combines both high dc and ac performance with its low offset voltage, high-gain bandwidth, low harmonic distortion, and low-noise characteristics. In addition, its output is capable of driving 600- $\Omega$  loads. All these characteristics make the device ideally suited for use in audio, active filtering, and industrial measurement applications.

#### **ORDERING INFORMATION**

T <sub>A</sub>	V <sub>IO</sub> (25°C, MAX)	PAC		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	Standard grade 1.5 mV	PDIP – P	Tube of 50	TL5580IP	TL5580IP
		SOIC - D	Tube of 75	TL5580ID	Z5580
			Reel of 2500	TL5580IDR	2000
		TSSOP – PW	Tube of 150	TL5580IPW	Z5580
-40°C to 85°C			Reel of 2000	TL5580IPWR	2000
-40 C 10 85 C	A grade 1 mV	PDIP – P	Tube of 50	TL5580AIP	TL5580AIP
			Tube of 75	TL5580AID	755904
		SOIC – D	Reel of 2500	TL5580AIDR	Z5580A
		TSSOP – PW	Tube of 150	TL5580AIPW	755904
		1330F - PW	Reel of 2000	TL5580AIPWR	- Z5580A

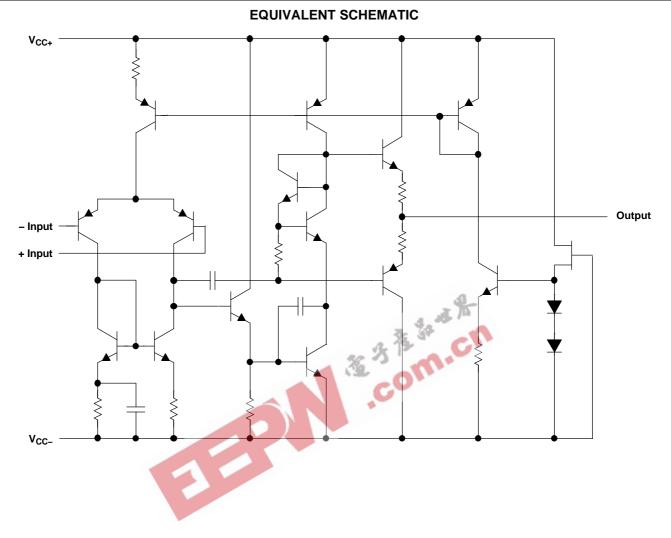
(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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#### Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{\text{CC}\pm}$	Supply voltage			±18	V
VI	Input voltage (any input)			±15	V
V <sub>ID</sub>	Differential input voltage			±30	V
I <sub>O</sub>	Output current			±50	mA
		D package		97	
$\theta_{JA}$	Package thermal impedance <sup>(2)(3)</sup>	P package		85	°C/W
			149		
TJ	Operating virtual junction temperature			150	°C
T <sub>stg</sub>	Storage temperature range		-60	125	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating" conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability. The package thermal impedance is calculated in accordance with JESD 51-7. (2)

(3)

#### **Recommended Operating Conditions**

	3 72 6	MIN	MAX	UN
Supply voltage		2	16	V
Supply voltage	-O**	-2	-16	v
Operating free-air temperature		-40	85	°C



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#### **Electrical Characteristics**

 $V_{CC\pm} = \pm 15 \text{ V}$  (unless otherwise noted)

PARAMETER			TEST CONDITIONS	T <sub>A</sub>	MIN	TYP	MAX	UNIT	
		TL5580A		25°C		0.3	1	mV	
	Input offset voltage	T LOOGUA	R <sub>S</sub> ≤ 10 kΩ	-40°C to 85°C			1.35		
V <sub>IO</sub>	input onset voltage	TL5580	$-R_{S} \leq 10 \text{ ksz}$	25°C		0.3	1.5		
		12000		–40°C to 85°C			2		
$\alpha V_{IO}$	Average temperature coefficient of input offset voltage			-40°C to 85°C		1.8	5	μV/°C	
	Input offect ourrept			25°C		5	75	nA	
I <sub>IO</sub>	Input offset current			–40°C to 85°C			100		
	Input biog ourrent			25°C		100	500	nA	
I <sub>IB</sub>	Input bias current			-40°C to 85°C			800		
A <sub>VD</sub>	Large-signal differential-voltage		$P > 2 k O V = \pm 10 V$	25°C	90	110		dB	
	amplification	-	$R_L \ge 2 \ k\Omega, \ V_O = \pm 10 \ V$	–40°C to 85°C	87			uБ	
M	O desta de se su las		$R_L \ge 2 k\Omega$	25°C	12.75 - 12.25	±13.5		V	
V <sub>OM</sub>	Output voltage swing		rl ≤ 2 k22	-40°C to 85°C	12.5 –12			V	
V	Common mode input velter			25°C	±13	±13.5		V	
V <sub>ICR</sub>	Common-mode input voltage range		Rs ≤ 10 kΩ.	-40°C to 85°C	±12			V	
CMRR	Common-mode rejection ratio		$R_{S} \leq 10 \text{ k}\Omega$	25°C	90	110		dB	
CIVIRR			$V_{ICR} = -12 \text{ V to } 12 \text{ V}$	–40°C to 85°C	85				
k <sub>SVR</sub> <sup>(1)</sup>	Supply-voltage rejection ratio		R <sub>S</sub> ≤ 10 kΩ	25°C	85	110		dB	
•SVR			NS 2 10 NS2	$-40^{\circ}C$ to $85^{\circ}C$	83				
1	Supply current (all amplifiers)			25°C		6	9	mA	
I <sub>CC</sub>				–40°C to 85°C			12		

(1) Measured with  $V_{CC\pm}$  varied simultaneously

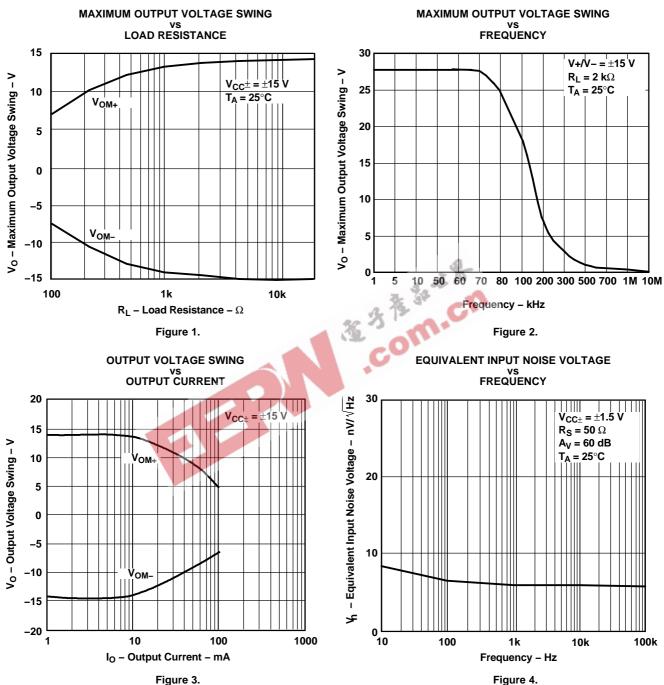
#### **Operating Characteristics**

 $V_{CC\pm}$  = ±15 V,  $T_{A}$  = 25°C (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	ТҮР	UNIT
SR	Slew rate at unity gain	$R_L \ge 2 \ k\Omega$	5	V/µs
GBW	Gain bandwidth product	f = 10 kHz	12	MHz
THD	Total harmonic distortion	$V_0 = 5 \text{ V}, \text{ R}_L = 2 \text{ k}\Omega, \text{ f} = 1 \text{ kHz}, \text{ A}_{VD} = 20 \text{ dB}$	0.0005	%
Vn	Equivalent input noise voltage	f = 1 kHz	7	nV/√Hz



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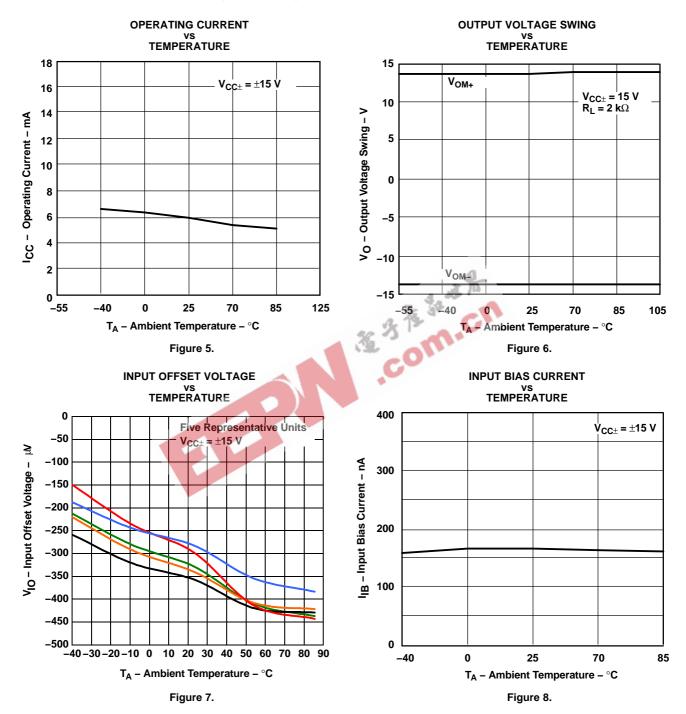


#### **TYPICAL CHARACTERISTICS**

Figure 4.



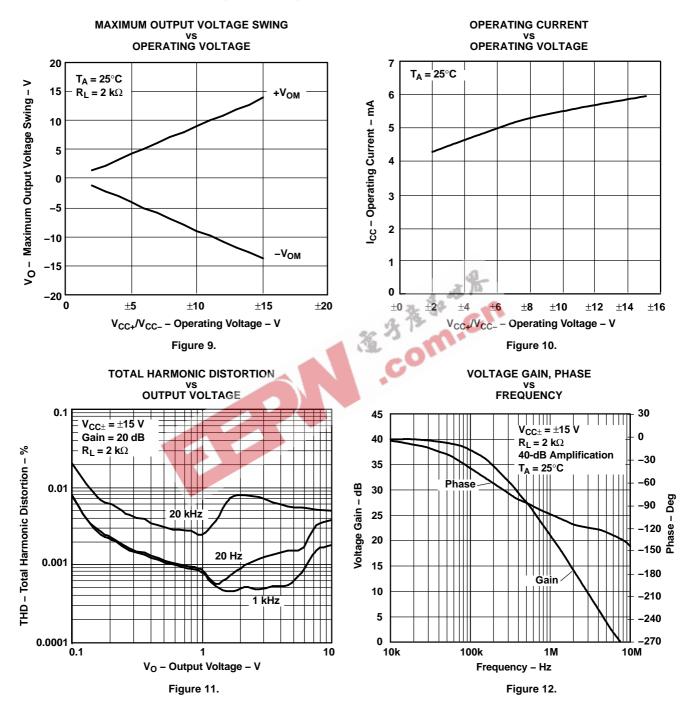
#### **TYPICAL CHARACTERISTICS (continued)**





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#### **TYPICAL CHARACTERISTICS (continued)**





# PACKAGE OPTION ADDENDUM

6-Dec-2006

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
TL5580AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL5580AIDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL5580AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL5580AIDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL5580AIP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL5580AIPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL5580AIPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL5580AIPWE4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL5580AIPWR	ACTIVE	TSSOP	PW	8	20 <b>00</b>	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL5580AIPWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL5580ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL5580IDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL5580IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL5580IDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL5580IP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL5580IPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL5580IPW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL5580IPWE4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL5580IPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL5580IPWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIN

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design. **PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



# PACKAGE OPTION ADDENDUM

6-Dec-2006

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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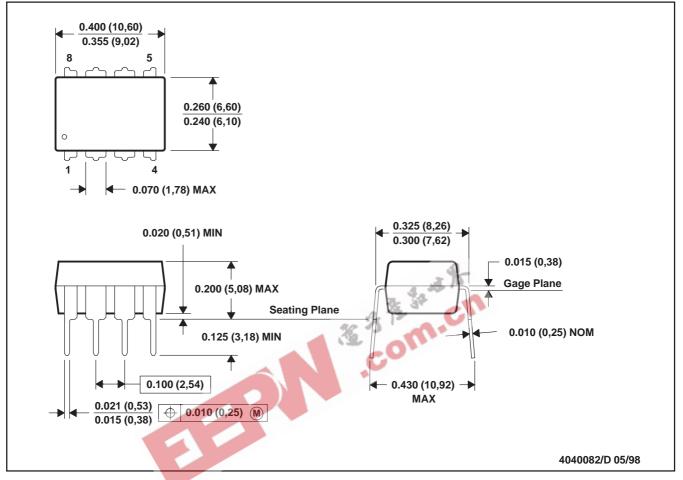


### **MECHANICAL DATA**

PLASTIC DUAL-IN-LINE

MPDI001A - JANUARY 1995 - REVISED JUNE 1999

P (R-PDIP-T8)



NOTES: A. All linear dimensions are in inches (millimeters).

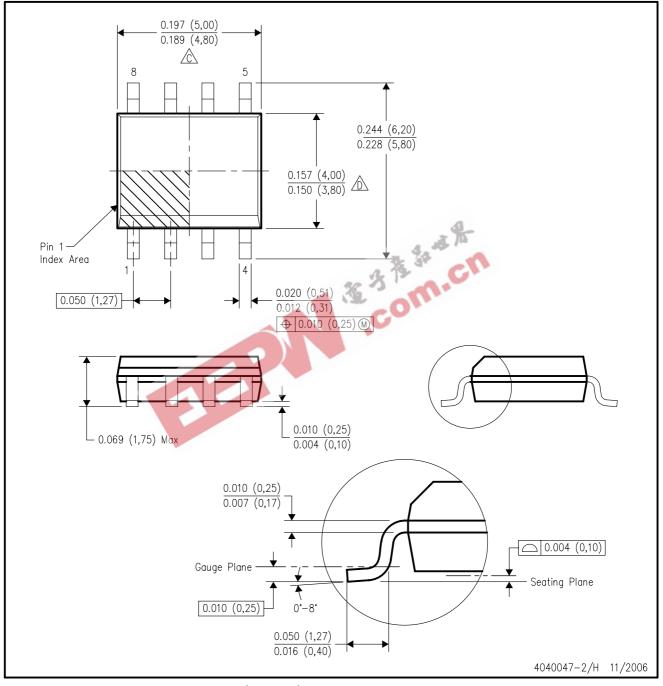
- B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg\_info.htm



D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.

🖄 Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

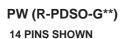
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.

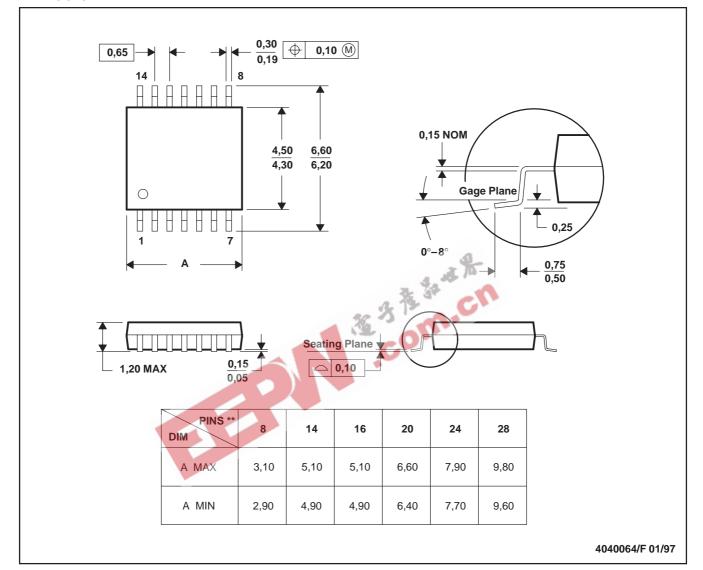


#### **MECHANICAL DATA**

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

#### PLASTIC SMALL-OUTLINE PACKAGE





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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Mailing Address:

Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

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